TITLE: White I Shape Underfilm (0.762mm (30 mils) wide x 5.842mm (230 mils) long x .229mm (9 mils) thick)						
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1. SCOPE

This document contains general Preco-Miwa requirements, and those specific mechanical requirements for this part.

2. DESCRIPTION AND APPLICATION

- 2.1 DESCRIPTION: This specification covers the material and packaging requirements for the black "I shaped" underfilm material.
- 2.2 APPLICATION: The film, which is machine placed prior to the BGA, helps to secure the edges of the BGA package during reflow thereby reducing the stress on the solder bumps during drop testing.

3. MATERIAL REQUIREMENTS

3.1 MATERIAL PROPERTIES

Physical Property Hardness Tensile Properties Tensile Stress @ 100% Elongation	Typical Properties 95 Shore A 1600psi 11.0MPa
Tensile Stress @	3500psi

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PRECO-MIWA NO. 10003 **MATERIAL or METHODS Specification** White I Shape Underfilm (0.762mm (30 mils) wide x 5.842mm (230 mils) long x TITLE: .229mm (9 mils) thick) 18-Jun-09 6 of 7 **REVISION DATE:** ISSUE: 0 PAGE: MEMO: 290678 FACTORY AUTOMATION AND IDENTIFICATION 3.3 Tape and Reel Packaging with the following conditions: 3.3.1 Tape Width: 12 mm 3.3.2 Tape Pitch (part to part): 4mm 3.3.3 Component Orientation: Film must be orientated into the tape pocket with the laser cut side (laser entry) facing the bottom of the pocket to prevent the material from sticking to the placement nozzle. The company converting the film material will identify the laser cut side with a label. \$ 1.50^{-0.10} 6.1 12.0 1.75±0.1 0 0 0 0 0 0 0 Ô 0 0 0 0 Ø 0 Ó 0.55.5 0.30 ± 0.05 40 1.0 SECTION C-C SCALE 2:1 All dimensions in mm Reel Diameter: 178mm (7 inch) 3.3.4 Must use conductive tape cover with PSA. 3.3.5 MATERIAL STORAGE, PACKAGING AND SHIPMENT 3.4

- 3.4.1 Material must be stored at 25°C (±5°C) and with relative humidity between 40 60%.
- 3.4.2 If these parts are to be packaged in tape and reel per Preco-Miwa specification, components must be sealed prior to shipment so as to prevent contamination and damage while en route to Motorola. Damaged containers will be documented by Preco-Miwa Receiving and follow up action with the carrier or supplier will occur when appropriate. I Any data should be correlated to the material received and be enclosed with the parts inside the packing container. When multiple packing containers are shipped as one lot, the box with the data
- 3.4.3 should be marked "DATA IN THIS CONTAINER".

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- 3.4.4 The product will be supplied to Preco-Miwa in approved packaging. This will be in order of preference: Reusable packaging
 - a.
 - Packaging made from recycled material b.
 - C. Packaging made from recyclable material
- 3.4.5 Toxic, ESD generating or non-degradable material should not be used..

Any packaging should be designed in collaboration with Preco-Miwa Engineering and manufacturing to maximize "design for manufacture". If possible, packaging should improve assembly techniques and reduce cycle times.

3.5 USER MANUFACTURING ENVIRONMENTS

All components must fully conform to electrical and mechanical specifications in Sections 6.3 and 6.4 after exposure to the manufacturing environments listed below for a minimum of three times. This maximum shall be determined by Preco-Miwa on a part-by-part basis, depending on whether or not the parts are to be reclaimed.

- 3.5.1 Component Handling: All necessary special handling techniques shall be adopted in order to avoid contamination of metallization / terminations. Examples include use of finger cots, plastic tweezers, etc.
- A placement force of up to 500 grams is applied (using a 2.00 mm or a 0.080 inch 3.5.2 Part Placement: diameter rod) to the center of the part while remaining in its tape carrier.
- Lead Free Processing: Small Body component requirements 3.5.3 unless otherwise determined.

Condition

Average ramp-up rate (25°C to 217 150 to 200°C > 217°C Time within 5°C of Peak Peak Temperature Cool-down rate (Peak to 50°C Time from 25°C to Peak

Exposure

Less than 3°C /second Between 60-180 seconds Between 60-150 seconds 20-40 seconds 250°C +0/-5°C Less than 6°C /second No greater than 480 seconds